

	Hit s	Search Text	DBs
29	3	(((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board) or PWB) near29 (dielectric or non\$4copper or (FR\$3 near3 insulat\$4))) and (((fill\$4 or deposit\$4 or embed\$5) near26 (via or hole or through\$4hole) near9 (capacit\$4 or dielectric or ((capacit\$4 or inorganic or resin) near9 (paste or material or composition or BaTiO\$2 or (barium near2 titanate)))))) same contact\$4 same bottom same top same electrode)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
30	3	(((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board) or PWB) near29 (dielectric or non\$4copper or (FR\$3 near3 insulat\$4))) and (((fill\$4 or deposit\$4 or embed\$5) near26 (via or hole or through\$4hole) near9 (capacit\$4 or dielectric or ((capacit\$4 or inorganic or resin or ceramic) near16 (paste or material or composition or BaTiO\$2 or (barium near2 titanate)))))) same contact\$4 same bottom same top same electrode)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
31	8	(((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board) or PWB) near29 (dielectric or non\$4copper or (FR\$3 near3 insulat\$4))) and (((fill\$4 or deposit\$4 or embed\$5) near26 (via or hole or through\$4hole) near9 (capacit\$4 or dielectric or ((capacit\$6 or inorganic or resin or ceramic) near16 (paste or material or composition or BaTiO\$2 or (barium near2 titanate)))) same bottom same top same electrode) and ((capacitor or ceramic or dielectric) same (contact\$4 or jxtapos\$3 or connect\$4) same ((copper or Cu) near13 (layer or film or laminate or foil) near26 (upper or top or cover) near22 (lower or bottom or multilayer))))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

	Hits	Search Text	DBs
32	8	(((print\$4 near9 (wiring or circuit\$4) near9 board) or PCB or ((circuit\$4 or wiring) near9 board) or PWB) near29 (dielectric or non\$4copper or (FR\$3 near3 insulat\$4) or FR\$3)) and (((fill\$4 or deposit\$4 or embed\$5) near26 (via or hole or through\$4hole) near9 (capacit\$4 or dielectric or ((capacit\$6 or inorganic or resin or ceramic) near16 (paste or material or composition or BaTiO\$2 or (barium near2 titanate)))) same bottom same top same electrode) and ((capacitor or ceramic or dielectric) same (contact\$4 or juxtapos\$3 or connect\$4 or attach\$3) same ((copper or Cu) near13 (layer or film or laminate or foil) near26 (upper or top or cover) near22 (lower or bottom or multilayer))))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB